

AM2520SRD03

SUPER BRIGHT RED

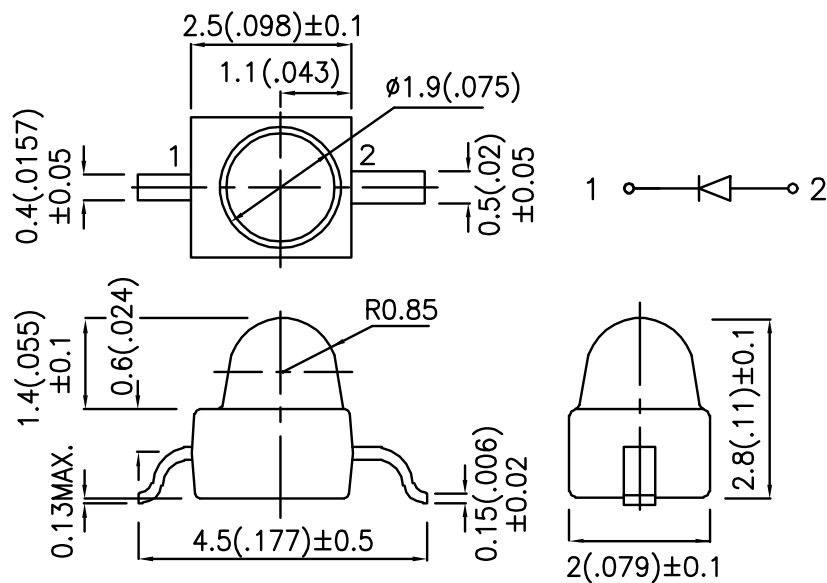
Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- GULL WING LEAD.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE : 1000PCS / REEL.
- RoHS COMPLIANT.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2 θ 1/2
AM2520SRD03	SUPER BRIGHT RED (GaAlAs)	RED DIFFUSED	50	150	40°

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at TA=25°C

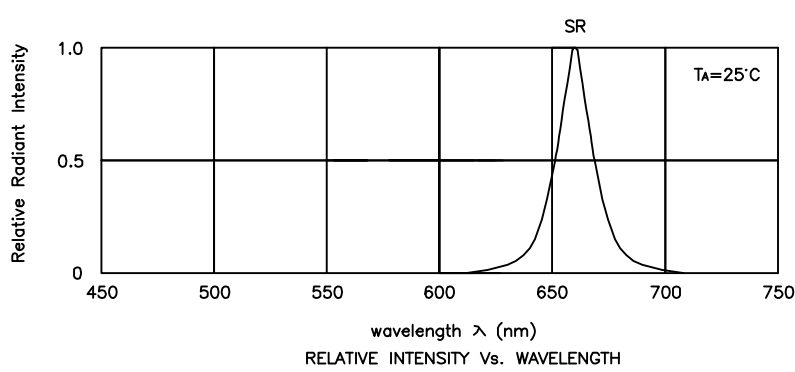
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Super Bright Red	660		nm	IF=20mA
λ_D	Dominant Wavelength	Super Bright Red	640		nm	IF=20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Red	20		nm	IF=20mA
C	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
VF	Forward Voltage	Super Bright Red	1.85	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Red		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

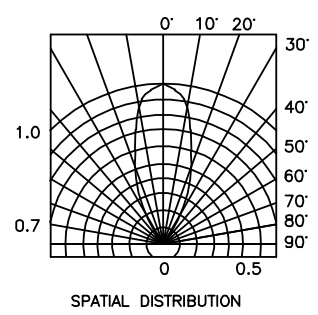
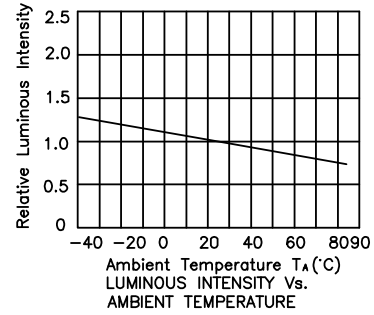
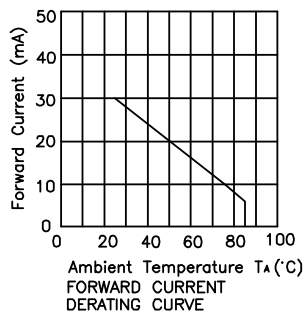
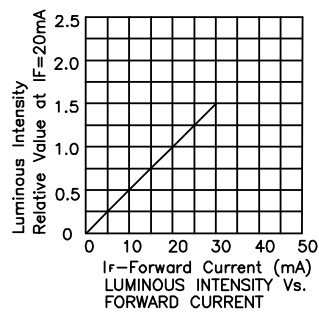
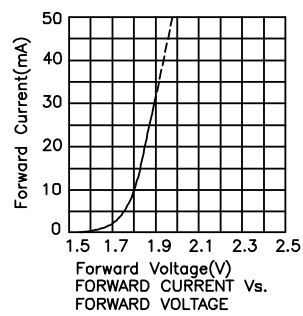
Parameter	Super Bright Red	Units
Power dissipation	100	mW
DC Forward Current	30	mA
Peak Forward Current [1]	155	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

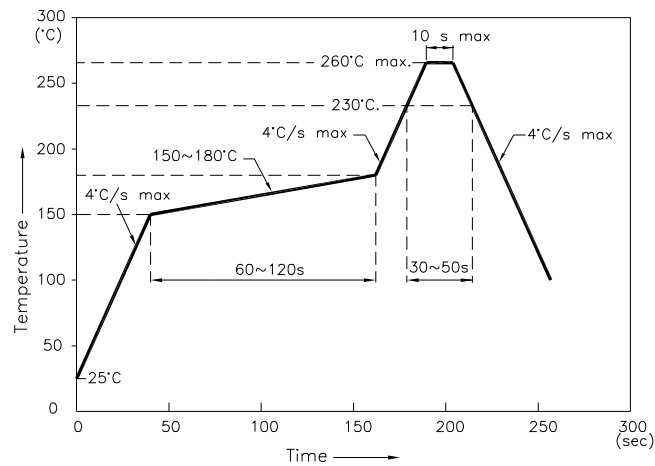


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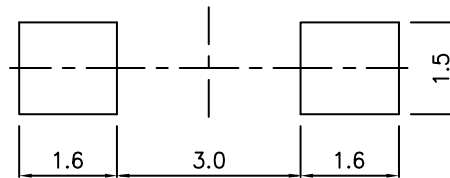
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature $245^{\circ}\text{C} (+/-5^{\circ}\text{C})$. The maximum soldering temperature should be limited to 260°C .
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

